

## ABSTRACT

Sub H1)

Semiconductor dice and passive components are connected to an interposer and then tested. If they pass the test, the interposer is connected to a substrate. If they do not pass the test, the interposer may be reworked or discarded without being connected to the substrate. In this manner, other devices on the substrate do not have to be sacrificed if the semiconductor dice and/or passive components are defective.